WHAT IS CLAIMED IS:

1. A switch, comprising:

   a) a switching fluid;

   b) a substrate having a plurality of signal conductors formed thereon, at least some of which are in contact with the switching fluid;

   c) a lid, covering the switching fluid and having a perimeter that intersects at least some of the signal conductors; and

   d) a thickfilm dielectric printed on the substrate below the perimeter of the lid; wherein the lid is mounted on the thickfilm dielectric.

2. The switch of claim 1, further comprising a conductive thickfilm printed on a top surface of the thickfilm dielectric, wherein the lid is electrically coupled to the conductive thickfilm.

3. The switch of claim 2, wherein the lid is soldered to the conductive thickfilm.

4. The switch of claim 2, wherein the lid is attached to the conductive thickfilm via a conductive adhesive.

5. The switch of claim 2, wherein the thickfilm dielectric is continuous about the perimeter of the lid.

6. The switch of claim 1, wherein a top surface of the thickfilm dielectric is polished.

7. The switch of claim 1, wherein the lid is conductive.

8. The switch of claim 1, wherein the lid is metallic.

9. A switch, comprising:

a) first and second mated substrates defining therebetween at least portions of a number of cavities;

b) a switching fluid, held within one or more of the cavities, that is movable between at least first and second switch states in response to forces that are applied to the switching fluid;

c) a plurality of signal conductors formed on the first substrate, extending from the one or more cavities holding the switching fluid;

d) a lid, attached to the first substrate and covering at least a portion of the second substrate; the lid having a perimeter that intersects at least some of the signal conductors; and

e) a thickfilm dielectric printed on the substrate below the perimeter of the lid; wherein the lid is mounted on the thickfilm dielectric.

10. The switch of claim 9, wherein:

a) the second substrate is a channel plate; and

b) the one or more cavities holding the switching fluid are at least partly defined by a bent switching fluid channel in the channel plate.

11. The switch of claim 10, wherein:

a) one of the signal conductors presents within the cavity defined by the bent switching fluid channel, at the bend; and

b) different ones of the signal conductors present within the cavity defined by the bent switching fluid channel, on either side of the bend.

12. The switch of claim 9, further comprising a conductive thickfilm printed on a top surface of the thickfilm dielectric, wherein the lid is electrically coupled to the conductive thickfilm.

13. The switch of claim 12, wherein the lid is soldered to the conductive thickfilm.

14. The switch of claim 12, wherein the lid is attached to the conductive thickfilm via a conductive adhesive.

15. The switch of claim 12, wherein the thickfilm dielectric is continuous about the perimeter of the lid.

16. The switch of claim 9, wherein a top surface of the thickfilm dielectric is polished.

17. The switch of claim 9, wherein the lid is conductive.

18. The switch of claim 9, wherein the lid is metallic.

19. A switch, comprising:

a) a switching element;

b) a substrate having a plurality of signal conductors formed thereon, at least some of which are in contact with said switching element;

c) a lid, covering the switching element and having a perimeter that intersects at least some of the signal conductors; and

d) a thickfilm dielectric printed on the substrate below the perimeter of the lid; wherein the lid is mounted on and heremetically sealed to the substrate via the thickfilm dielectric.

20. The switch of claim 19, further comprising a conductive adhesive between said lid and said thickfilm dielectric.